

IEEE EPS Technical Webinar with Universiti Sains Malaysia

26th June 2024



The graphic features the IEEE EPS logo on the left, the title 'EPS Webinar Series 2024' in the center, and the IEEE logo with the tagline 'Advancing Technology for Humanity' on the right. Below the title is the webinar topic 'Failure Analysis of Engineering Materials for Advanced Packaging'. A portrait of Prof. Kuan Yew Cheong is shown on the left, with his name and affiliation below it. A large paragraph of text describes the webinar's focus on failure analysis in advanced packaging. On the right, a box contains the date, time, platform, a 'REGISTER NOW!' button with a QR code, and a 'SCAN ME' button. The IEEE website URL is at the bottom right.

IEEE ELECTRONICS PACKAGING SOCIETY

EPS Webinar Series 2024

Failure Analysis of Engineering Materials for Advanced Packaging

Failure is unavoidable in high volume manufactured engineering products, which includes advanced packages for numerous applications to address the competitive needs in the era of digitization and electrification. In order to minimize failure and to improve quality, robustness, durability, reliability, and safety of a product, investigation of failure is an important and yet complex and complicated activity that requires integration of diverse knowledge in science and engineering by inter-relating fundamental and technological knowledge of engineering materials, processes, and operation principles of the product. As more diverse, complex, and conflict engineering materials with complicated geometry and distinctive difference in dimension, interactions of engineering materials within an advanced package are getting complicated. Hence, a systematic, effective, and data-driven approach must be adopted in failure analysis. In this lecture, basic strategy and essential knowledge required to create postulation, verification, and confirmation of failures, subsequently to establish failure mechanisms, and finally to identify root causes of failures in advanced packaging will be elaborated. Fundamental understanding of critical property, performance, and characterization will be correlated to failures in advanced packaging. Potential challenges in failure analysis will be briefly presented at the end of the lecture.

Prof. Kuan Yew CHEONG
School of Materials & Mineral Resources Engineering
Universiti Sains Malaysia

Date: 26 June 2024 (Wed)
Time: 10 – 11 am (Malaysia, GMT +8:00)
Platform: IEEE CISCO WebEx

REGISTER NOW!
(Click the link/icon the QR for registration)
*E certificates will be provided to all participant.

SCAN ME

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- IEEE EPS Malaysia has successfully organized a Technical Webinar with Prof Cheong Kuan Yew from School of Materials and Mineral Resources Engineering, Universiti Sains Malaysia, on the topic of Failure Analysis of Engineering Materials for Advanced Packaging.
- Prof Cheong expounded on fundamental understanding of critical property, performance, and characterization correlated to failures in semiconductors advanced packaging.
- > 30 participants joined the webinar with strong engagement from the audience.

